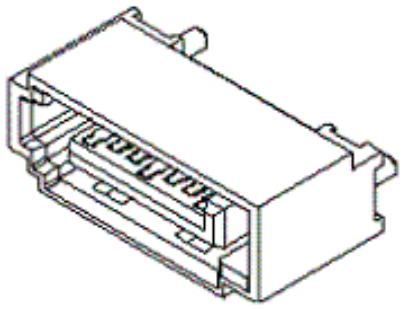
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PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0678005003
Status: Active
Overview: serial_ata_products
Description: PURE TIN 1.27MM PITCH VERTICLE SMT



Series image - Reference only

Documents:
3D Model
Drawing (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR 19980
UL	E29179

General

Product Family	PCB Headers
Series	67800
Application	Board-to-Board, Wire-to-Board
Comments	Staggered Solder Pin|Metal Post Length 2.65mm (.104")
Overview	serial_ata_products
Product Name	Serial ATA

Physical

Breakaway	No
Circuits (Loaded)	7
Circuits (maximum)	7
Color - Resin	Blue
Durability (mating cycles max)	50
First Mate / Last Break	Yes
Flammability	94V-0
Glow-Wire Compliant	No
Guide to Mating Part	No
Keying to Mating Part	Yes
Lock to Mating Part	Yes
Material - Metal	Brass
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Rows	1
Orientation	Vertical
PCB Locator	Yes
PCB Retention	Yes
Packaging Type	Tray
Pitch - Mating Interface (in)	0.050 In
Pitch - Mating Interface (mm)	1.27 mm
Pitch - Term. Interface (in)	0.050 In
Pitch - Term. Interface (mm)	1.27 mm
Plating min: Mating (µin)	15
Plating min: Mating (µm)	0.38
Plating min: Termination (µin)	75
Plating min: Termination (µm)	1.9
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Shrouded	Fully
Stackable	No
Temperature Range - Operating	-35°C to +85°C
Termination Interface: Style	Surface Mount

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Halogen-Free

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
67800Series

Electrical

Current - Maximum per Contact	1.5A
Voltage - Maximum	15V DC

Solder Process Data

Duration at Max. Process Temperature (seconds)	3
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	255

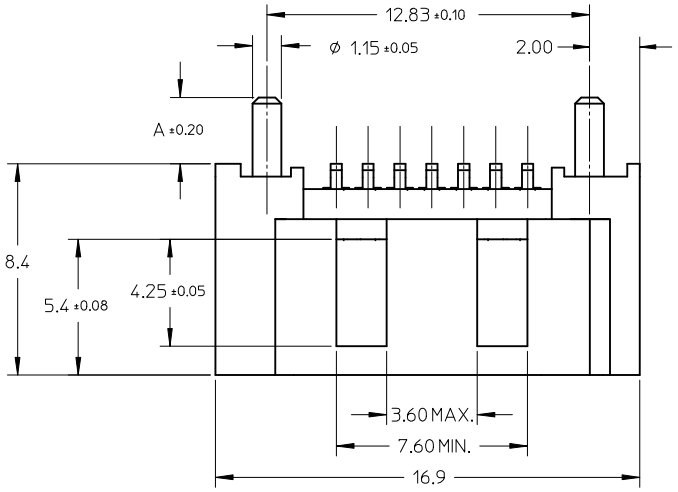
Material Info

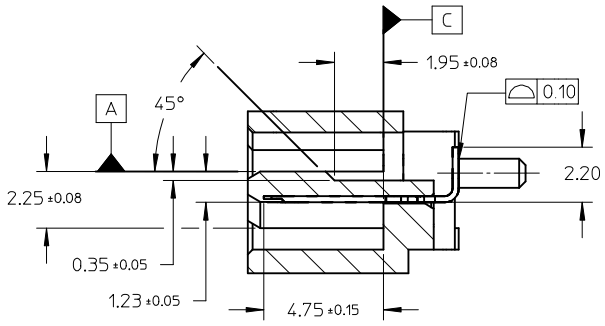
Reference - Drawing Numbers

Packaging Specification	PK-67800-001
Sales Drawing	SD-67800-005

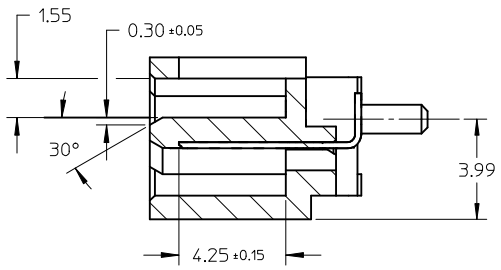
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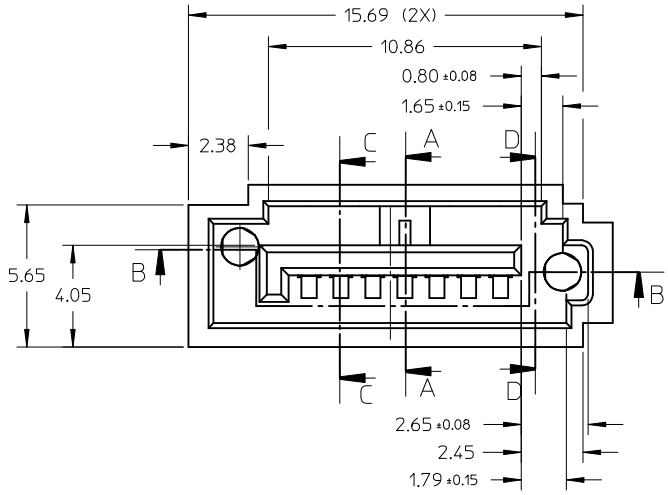


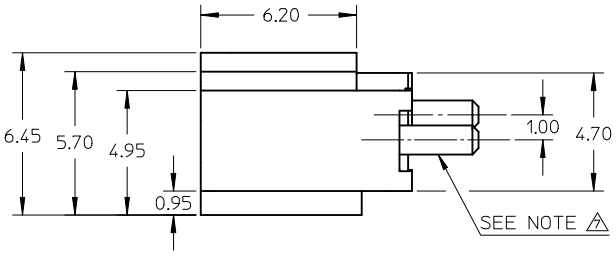


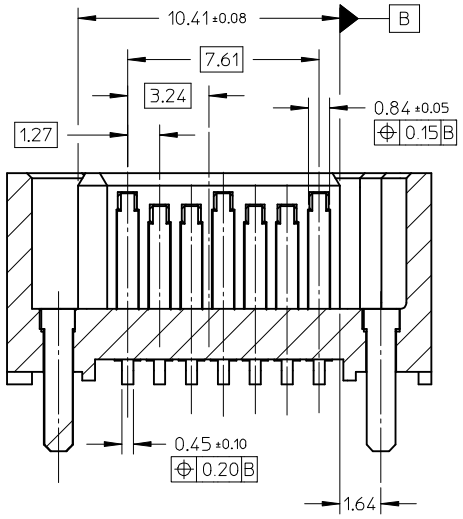
SECTION A-A



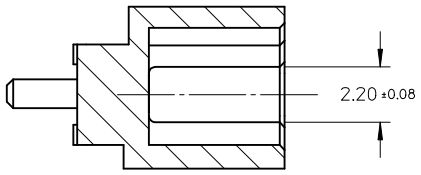
SECTION C-C







SECTION B-B



SECTION D-D

REVISED				REV
EC NO: SH2010-0043	2009/08/07			
DRWN:GLI	2009/08/10			
CHKD:XJSONG	2009/09/13			
APPR:RZHANG				
DESCRIPTION				

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 1 °		

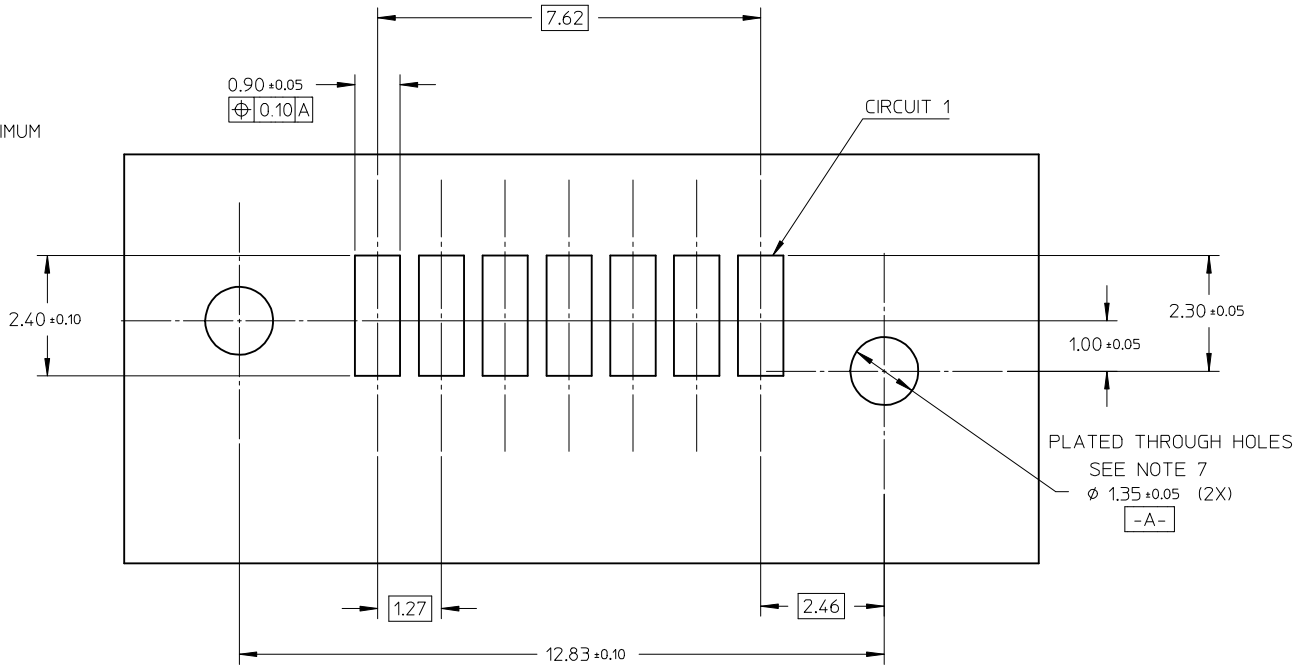
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: 5:1	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: GRATE MA — DATE: 2004/02/02	TITLE: HIGH SPEED CONNECTOR 1.27MM PITCH VERTICAL SMT SOLDER TAIL		
CHECKED BY: YAJUN — DATE: 2004/02/02			
APPROVED BY: SAM — DATE: 2004/02/02	MOLEX INCORPORATED		
MATERIAL NO.: SEE SHEET 2	DOCUMENT NO.: SD-67800-005	SHEET NO.: 1 OF 2	

SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

NOTES:

1. MATERIAL:
   HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, GLASS FILLED, UL94V-0, COLOR: REFER TO CHART.
   TERMINAL: BRASS
   POST: BRASS
2. TERMINAL PLATING:
   CONTACT AREA: (a) GOLD FLASH
   (b) GOLD, THICKNESS=0.76 MICRON MINIMUM
   (C) GOLD, THICKNESS=0.38 MICRON MINIMUM
   SOLDER TAIL: TIN, THICKNESS=1.27 MICRON MINIMUM
   UNDER PLATE: NICKEL PLATED, THICKNESS=1.27 MICRON MINIMUM
3. POST PLATING: UNDER PLATE: NICKEL, THICKNESS=1.25 MICRON MINIMUM
   TIN, THICKNESS=1.9 MICRON MINIMUM OVER ALL
4. PACKAGING: PK-67800-001
5. PRODUCT SPECIFICATION REFER TO PS-67491-001
6. RECOMMENDED SOLDERING PROCESS: IR PROCESS
7. ⚠ METAL POSTS TO BE SOLDERED TO PCB



RECOMMENDED P.C.B LAYOUT
CONNECTOR SIDE

MATERIAL NO	PLATING TYPE	HOUSING COLOR	DIM A	REMARK
678005025	SEE NOTE2(c)	BLACK	3.45	PURE TIN
678005022	SEE NOTE2(b)			
678005021	SEE NOTE2(a)			
678005015	SEE NOTE2(c)	BLACK	3.05	
678005012	SEE NOTE2(b)			
678005011	SEE NOTE2(a)			
678005005	SEE NOTE2(c)	BLACK	2.65	
678005004	SEE NOTE2(c)	YELLOW		
678005003	SEE NOTE2(c)	BLUE		
678005002	SEE NOTE2(b)	BLACK		
678005001	SEE NOTE2(a)			

REVISED
EC NO: SH2010-0043 2009/08/07
DRWN:GLI I 2009/08/10
CHKD:XJSONG 2009/09/13
APPR:RZHANG
DESCRIPTION
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.15	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 5:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: GRATE MA DATE: 2004/02/02
CHECKED BY: YAJUN DATE: 2004/02/02
APPROVED BY: SAM DATE: 2004/02/02

TITLE: HIGH SPEED CONNECTOR 1.27MM PITCH VERTICAL SMT SOLDER TAIL

molex MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-67800-005
SHEET NO.: 2 OF 2
SIZE: A3

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